CUI DEVICES

date 02/13/2020

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SERIES: HSS-B20-0635 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- solder pin for secure PCB mounting
- round hole for component attachment
- black anodized finish





MODEL	thermal resistance ¹				power dissipation ¹	
	fin height (mm)	<pre>@ 75°C ΔT, nat conv (°C/W)</pre>	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS-B20-0635H	6.35	28.85	35.46	10.68	7.88	2.60
HSS-B20-0635H-01	9.53	27.78	33.93	9.51	6.84	2.70
HSS-B20-0635H-02	12.70	29.09	33.89	10.49	6.81	2.58

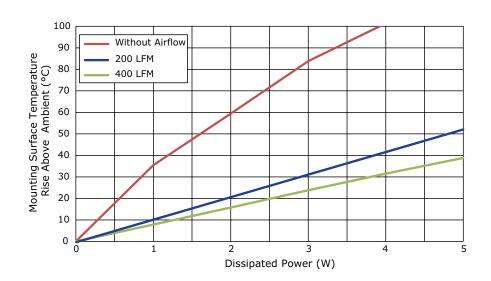
Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

HSS-B20-0635H

	Heatsink Temperature Rise Above Ambient ($\Delta T = Ths - Ta$) (°C)			
Power (W)	Natural Conv.	200 LFM	400 LFM	
0	0	0	0	
1	35.46	10.68	7.88	
2	59.42	20.81	15.77	
3	83.82	31.59	23.83	
4	101.40	41.80	31.52	
5	122.52	52.02	38.83	

Ths: "hot spot" temperature measured on the heatsink Ta: ambient temperature

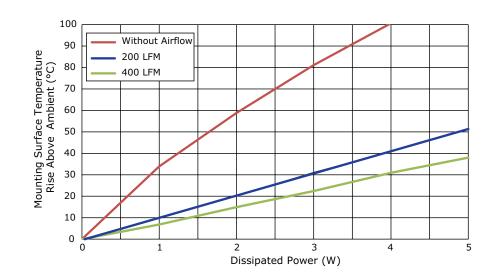


PERFORMANCE CURVES (CONTINUED)

HSS-B20-0635H-01

	Heatsink Temperature Rise Above Ambient ($\Delta T = Ths - Ta$) (°C)			
Power (W)	Natural Conv.	200 LFM	400 LFM	
0	0	0	0	
1	33.93	9.51	6.84	
2	58.86	20.45	14.91	
3	81.12	31.36	22.45	
4	100.66	40.98	30.96	
5	121.15	51.38	38.04	

Ths: "hot spot" temperature measured on the heatsink

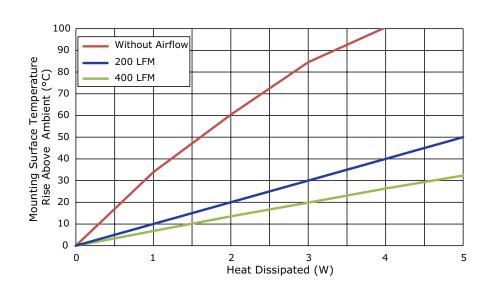


HSS-B20-0635H-02

	Heatsink Temperature Rise Above Ambient ($\Delta T = Ths - Ta$) (°C)			
Power (W)	Natural Conv.	200 LFM	400 LFM	
0	0	0	0	
1	33.89	10.49	6.81	
2	60.40	20.20	13.50	
3	84.56	30.26	19.87	
4	100.59	40.17	26.37	
5	112.14	49.67	32.37	

Ths: "hot spot" temperature measured on the heatsink

Ta: ambient temperature

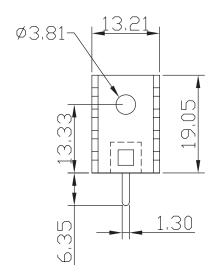


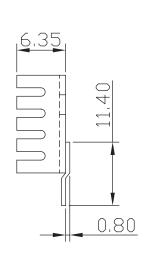
MECHANICAL DRAWING

units: mm tolerance: ±0.5 mm

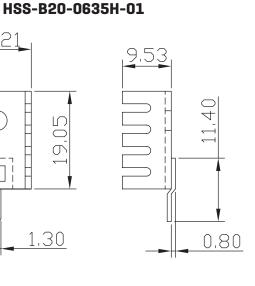
MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	HSS-B20-0635H: 1.5 g HSS-B20-0635H-01: 1.7 g HSS-B20-0635H-02: 2.0 g

HSS-B20-0635H

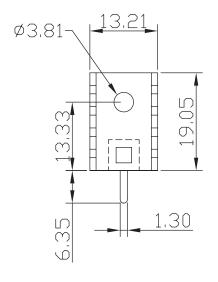


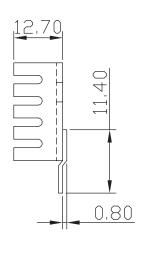


Ø3.81- σ 1.30



HSS-B20-0635H-02





Additional Resources: Product Page | 3D Model | PCB Footprint

CUI Devices | SERIES: HSS-B20-0635 | DESCRIPTION: HEAT SINK date 02/13/2020 | page 4 of 4

REVISION HISTORY

rev.	description	date
1.0	initial release	03/29/2017
1.01	brand update	02/13/2020

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

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